

Applicant : Osterheld et al.
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176. The polishing pad of claim 58, wherein the upper layer has a thickness between about 0.07 inches.

186. The polishing pad of claim 55, wherein the grooves are substantially circular and are concentrically arranged.

196. The polishing pad of claim 55, wherein the polishing surface is substantially circular.

206. The polishing pad of claim 55, wherein the grooves includes sidewalls that are substantially perpendicular to the polishing surface.

REMARKS

Attached is a marked-up version of the changes being made by the current amendment.

Applicant asks that all claims be examined.

Please apply any other charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

Date: 4/29/07



David J. Goren
Reg. No. 34,609
Telephone: (650) 839-5070
Facsimile: (650) 839-5071

Version with markings to show changes made

In the claims:

Claims 55-62 have been added:

55. A polishing pad for polishing a substrate in a chemical mechanical polishing system, comprising:

a polishing surface having a plurality of grooves, the grooves having a depth of 0.03 inches, a width of 0.02 inches, and a pitch between about 0.09 and 0.24 inches.

56. The polishing pad of claim 55, wherein the grooves are uniformly spaced over the polishing surface.

57. The polishing pad of claim 55, wherein the grooves have a pitch of 0.12 inches.

58. The polishing pad of claim 55, wherein the polishing pad further comprises an upper layer and a lower layer, the grooves being formed in the upper layer.

59. The polishing pad of claim 58, wherein the upper layer has a thickness between about 0.07 inches.

60. The polishing pad of claim 55, wherein the grooves are substantially circular and are concentrically arranged.

61. The polishing pad of claim 55, wherein the polishing surface is substantially circular.

62. The polishing pad of claim 55, wherein the grooves includes sidewalls that are substantially perpendicular to the polishing surface.